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Height (mm) Anodising Color B-Black C-Clear

Z-Custom

Ex.order code - 12

## Notes:

- Mentioned models are an extraction of full product range.

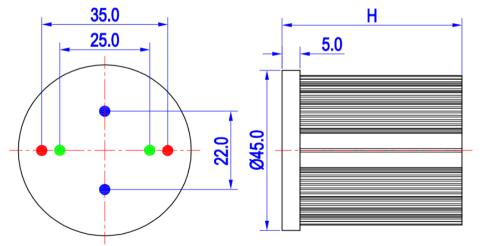
means option 1 and 2 combined

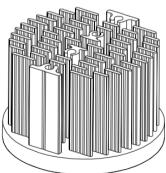
details Combinations available

Mounting Options - see graphics for

- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	Ergon COB (15.85×15.85)	/	M3	6.5mm	22.0mm/ 2-@180°
2	Ergon COB (17.85×17.85)	/		6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
	Ergon COB (15.85×15.85)	BJB Holder 47.319.6104.50	M3		
		Ideal Holder 50-2001CR			
3	AC-ALL Series	Lumens		6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	Ergon COB (17.85×17.85)	BJB Holder 47.319.2131.50	М3		
		Ideal Holder 50-2101CR			





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xLED-LUME-4530 Pin Fin Heat Sink Ø60mm for Lumens

## The product deta table

xLED	Model No.	xLED-LUME-4530
	Heatsink Size	Φ45xH30mm
	Heatsink Material	AL1070
Contra State	Finish	Black Anodized
	Weight (g)	45.0
	Dissipated power (Ths-amb,50℃)	7.0 (W)
	Cooling surface area (mm <sup>2</sup> )	22830
	Thermal Resistance (Rhs-amb)	7.14 (°C/W)

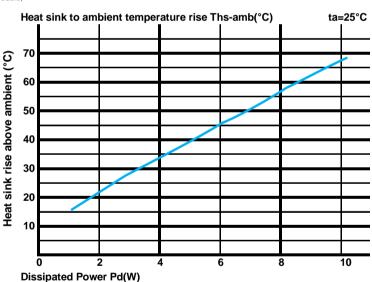
## The thermal data table

\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

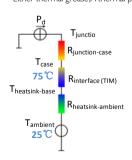
\*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (I - \eta L)$ .

Pd - Dissipated power ; Pe - Electrical power ;  $\eta L =$  Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-LUME-4530	
Dissipated Power Pd(W)	2.0	10.50	21.0
	4.0	8.50	34.0
	6.0	7.50	45.0
	8.0	7.00	56.0
	10.0	6.70	67.0



\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths - Ta)/Pd$ 

 $\theta\,$  - Thermal Resistance [°C/W] ;  $\,$  Ths - Heatsink temperature ;  $\,$  Ta - Ambient temperature ;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{\text{junction-case}}$ , the thermal resistance of the TIM outside the package is  $R_{\text{interface (TIM)}}$  [°C/W], the thermal resistance with the heat sink is  $R_{\text{heatsink-ambent}}$  [°C/W], and the ambient temperature is  $T_{\text{ambent}}$  [°C].

\*Thermal resistances outside the package  $R_{interface (TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:  $T_{junction}=(R_{junction-case}+R_{case-ambient})$ Pd+ $T_{ambient}$ 

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